

AMENDMENTS TO THE CLAIMS:

Listing of claims:

This listing of claims replaces all prior versions and listings of claims in the application.

Claim 1 (Original) A method of mounting an electronic component on a substrate, comprising:

placing the electronic component on the substrate with a solid support interposed between the electronic component and the substrate so as to space a terminal conductor of the electronic component from a corresponding terminal pad on the substrate;

melting a conductive bonding material on the terminal pad; and thereafter

melting the solid support so as to move down the electronic component toward the substrate, thereby contacting the terminal conductor with the conductive bonding material melting on the corresponding terminal pad.

Claim 2 (Original) The method according to claim 1, wherein said solid support is made of a thermoplastic resin material having a melting point higher than that of the conductive bonding material.

Claim 3 (Original) The method according to claim 1, wherein said conductive bonding material comprises solder particles dispersed in a flux including an organic solvent.

Claim 4 (Original) The method according to claim 1, wherein said solid support has an adherent property on its surface.

Claim 5 (Original) A method of mounting an electronic component on a substrate, comprising:

melting a conductive bonding material on a terminal pad on the substrate under a high temperature atmosphere; and

contacting a terminal conductor of the electronic component on the conductive bonding material on the terminal pad continuously under the high temperature atmosphere.

Claim 6 (Original) The method according to claim 5, further comprising:

placing the electronic component on the substrate, prior to melting of the conductive bonding material, with a solid support interposed between the electronic component and the substrate so as to space the terminal conductor from the terminal pad; and

melting the solid support so as to move down the electronic component toward the substrate, thereby contacting the terminal conductor with the conductive bonding material on the corresponding terminal pad, when the terminal conductor is contacted on the terminal pad.

Claim 7 (Original) The method according to claim 6, wherein said solid support is made of a thermoplastic resin material having a melting point higher than that of the conductive bonding material.

Claim 8 (Original) The method according to claim 7, wherein said solid support has an adherent property on its surface.

Claim 9 (Original) The method according to claim 5, wherein said conductive bonding material comprises solder particles dispersed in a flux including an organic solvent.

Claim 10 (Original) A method of mounting an electronic component on a substrate, comprising:
melting a solder paste on a terminal pad on the substrate; and
placing a terminal conductor of the electronic component on the solder paste on the terminal pad, said solder paste being kept melted.

Claim 11 (Original) The method according to claim 10, further comprising:
setting the electronic component on the substrate, prior to melting of the solder paste, with a solid support interposed between the electronic component and the substrate so as to space the terminal conductor from the terminal pad; and
melting the solid support so as to move down the electronic component toward the substrate, thereby contacting the terminal conductor with the solder paste on the corresponding terminal pad, said solder paste being kept melted.

Claim 12 (Original) The method according to claim 11, wherein said solid support is made of a thermoplastic resin material having a melting point higher than that of the solder paste.

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Claim 13 (Original) The method according to claim 12, wherein said solid support has an adherent property on its surface.

Claims 14-19 (Canceled)